a semiconductor laser chip whose bottom is die-bonded to a bonding surface with a conductive die-bonding paste, said semiconductor laser chip of the semiconductor laser apparatus including a light-emitting point at each of opposed end surfaces thereof,

wherein the conductive die-bonding paste adheres to a lower part of each end surface of the chip from the bottom up to a height below the light emitting point so that when the apparatus is used in the optical pickup an auxiliary beam directed from an optical disk to the lower part of one of the end surfaces is scattered by the conductive die-bonding paste adhering thereto.

REMARKS

This is in response to the Office Action dated March 13, 2003.

Claims 1, 13 and 14 stand rejected under Section 112, second paragraph. It is respectfully submitted that the claim changes herein address and overcome any potential issue in this respect without narrowing the claims.

Attached hereto is a marked-up version of the changes made to the claim(s) by the current amendment. The attached page(s) is captioned "**Version With Markings To Show Changes Made.**"

Claims 1-3 and 11-16 stand rejected under Section 102(e) as being allegedly anticipated by Kohashi (US 2001/0002916). This Section 102(e) rejection is respectfully traversed for at least the following reasons.

Kohashi is not prior art to the instant application. Kohashi has a 102(e) date of November 30, 2000, which is well after the priority date (Feb. 2000) of the instant

application. A certified English translation of the instant priority document is enclosed herewith. Thus, the Section 102(e) rejection must be withdrawn.

For at least the foregoing reasons, it is respectfully requested that all rejections be withdrawn. The application is in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

Respectfully submitted,

NIXON & VANDERHYE P.C.

By: _____
Joseph A. Rhoa
Reg. No. 37,515

JAR:caj
1100 North Glebe Road, 8th Floor
Arlington, VA 22201-4714
Telephone: (703) 816-4000
Facsimile: (703) 816-4100

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

1. (Amended) A semiconductor laser apparatus comprising a semiconductor laser chip whose bottom is die-bonded to a bonding surface with a conductive die-bonding paste, said semiconductor laser chip having a light-emitting point at each of opposed end surfaces thereof,

wherein the conductive die-bonding paste adheres to a lower part of each end surface of the chip, and a highest position of the conductive die-bonding paste on said lower part of each end surface of the semiconductor laser chip is at a height of more than 0.01 mm from the bonding surface and hence from the bottom of the semiconductor laser chip, but is below the light-emitting point of the semiconductor laser chip of the semiconductor laser apparatus.

13. (Amended) A semiconductor laser apparatus comprising:

a semiconductor laser chip die-bonded to a bonding surface with a conductive die-bonding paste, said semiconductor laser chip having a light-emitting point at at least one end surface thereof so as to provide a semiconductor laser apparatus,

wherein a highest position at which the conductive die-bonding paste adheres to at least one end surface of the semiconductor laser chip is at a height of more than 0.01 mm from the bonding surface, but is below the light-emitting point of the semiconductor laser chip; and

wherein the conductive die-bonding paste comprises epoxy resin and at least 80% by weight conductive filler of metal particles or flakes.

14. (Amended) A semiconductor laser apparatus for use in an optical pickup using a three-beam scheme for optical disks, the semiconductor [layer]laser apparatus comprising:

a semiconductor laser chip whose bottom is die-bonded to a bonding surface with a conductive die-bonding paste, said semiconductor laser chip of the semiconductor laser apparatus including a light-emitting point at each of opposed end surfaces thereof,

wherein the conductive die-bonding paste adheres to a lower part of each end surface of the chip from the bottom up to a height below the light emitting point so that when the apparatus is used in the optical pickup an auxiliary beam directed from an optical disk to the lower part of one of the end surfaces is scattered by the conductive die-bonding paste adhering thereto.